

# Model DS-750 -300 / DA-750 -300

## Die Sorter / Die Bonder

### Main Features:

- > High precision linear movement Pick & Place system
- > Fully programmable Rotary Pick & Place Head
- > Dual independent top view CCTV with zoom lenses at pick and place sites
- > Post pick up looking CCTV with zoom lens
- > Precise control of bonding force from 20 to 2000 grams
- > Precise control of Z-contact speed and timing
- > Flexible with quick conversion for 300mm/200mm dia. input Wafer sizes, or to pick from Waffle Trays
- > Flexible with quick conversion for output to Waffle Tray / Gel-pack / Wafer Ring or Frame
- > Option for Automatic Input Wafer Loader
- > Programmable Output Magazine Elevators and Feeder
- > Wafer /Tray ID recognition with Map processing capability
- > Real time process monitoring
- > Graphical user interface menu with dual color LCD displays



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## BASIC SPECIFICATIONS:

### - System performance

Die Size	20 - 800 mils (0.5 - 20 mm)
Placement Accuracy (XY)	+/- 1.0mil (+/-25 um)
Placement Accuracy (Theta)	+/- 0.25 deg

### - Rotary Pick & Place Head

Angular Travel	+/- 150 deg
Maximum Z Travel	2.50" (64 mm)
Bond Force	50 -2000 gr

### - Input Capability

Wafer Size	4"-12" (100mm-300 mm) dia
Wafer Mount Type	Metal Frame / Plastic 4"-6" dia. Ring
Waffle Trays	2" - 6 " (50mm-150 mm)

### - Output Capability

Waffle Trays	2" - 6" (50mm - 150mm)
Plastic Ring	4" - 6" dia.
Metal Frame	Up to 276mm width
Tape &-Reel Handler	8 - 56 mm wide

### - User Interface

Display Screen	Dual 17" SVGA Color LCD
Input Device	PC Track Ball and Keypad

### - Software

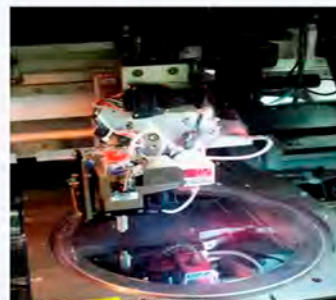
Operating Platform	MS Win-XP
External Map Input	Capable to process industry most common formats
Video Processing	256 Grey Scale, 1/4 Pixel accuracy

### - Utility, Size and Weight

Power	220V/110V, 2000 Watts
Compressed Air	70 PSI
Physical dimension	48"(W)x54"(D)x65"(H) 1219mm(W)x1372mm(D)x1650mm(H)
Weight	1200 Kg

## OPTIONAL MODULES:

Epoxy Dispensing System	Transfer Stamp from a Rotary Reservoir Precision Time-Pressure Controlled Needles Precision Pen Writing Needle
Automatic Wafer Loader	to auto-load Wafer or Tray Carrier from/to Magazine
Output Tape & Reel Handler	for Sorting to Tape Carrier
Post-pick Die Flipper	for Flip Chip application



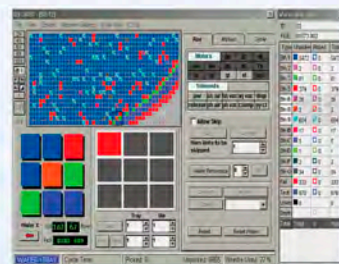
Rotary P&P Head



Wafer to Tray Sorter



Wafer to Wafer Sorter



GUI Menu and Mapping

## Headquarters & Factory

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